Switching Transistor

PNP Silicon

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-40	Vdc
Collector – Base Voltage	V _{CBO}	-40	Vdc
Emitter-Base Voltage	V_{EBO}	-5.0	Vdc
Collector Current – Continuous	Ι _C	-600	mAdc
Collector Current – Peak	I _{CM}	-900	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) @T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

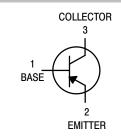
*Transient pulses must not cause the junction temperature to be exceeded. 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.

2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



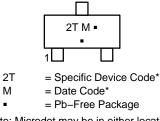
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MARKING DIAGRAM



(Note: Microdot may be in either location)

*Specific Device Code, Date Code or overbar orientation and/or location may vary depending upon manufacturing location. This is a representation only and actual devices may not match this drawing exactly.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT4403LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
SMMBT4403LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBT4403LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

C	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					-
Collector – Emitter Breakdown Voltage	(Note 3) $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-40	-	Vdc
Collector-Base Breakdown Voltage	$(I_{C} = -0.1 \text{ mAdc}, I_{E} = 0)$	V _{(BR)CBO}	-40	-	Vdc
Emitter-Base Breakdown Voltage	$(I_{E} = -0.1 \text{ mAdc}, I_{C} = 0)$	V _{(BR)EBO}	-5.0	-	Vdc
Base Cutoff Current	$(V_{CE} = -35 \text{ Vdc}, V_{EB} = -0.4 \text{ Vdc})$	I _{BEV}	-	-0.1	μAdc
Collector Cutoff Current	$(V_{CE} = -35 \text{ Vdc}, V_{EB} = -0.4 \text{ Vdc})$	I _{CEX}	-	-0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 3) (Note 3)		hFE	30 60 100 100 20	- - 300 -	-
Collector – Emitter Saturation Voltage	V _{CE(sat)}		-0.4 -0.75	Vdc	
Base – Emitter Saturation Voltage (Note 3) $ (I_C = -150 \text{ mAdc}, I_B = -15 \text{ mAdc}) $ $ (I_C = -500 \text{ mAdc}, I_B = -50 \text{ mAdc}) $		V _{BE(sat)}	-0.75	-0.95 -1.3	Vdc
SMALL-SIGNAL CHARACTERISTIC	S				
Current-Gain - Bandwidth Product	$(I_{C} = -20 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 100 \text{ MHz})$	f _T	200	-	MHz
Collector-Base Capacitance	$(V_{CB} = -10 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$	C _{cb}	-	8.5	pF
Emitter-Base Capacitance	$(V_{BE} = -0.5 \text{ Vdc}, I_{C} = 0, f = 1.0 \text{ MHz})$	C _{eb}	-	30	pF
Input Impedance	$(I_{C} = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h _{ie}	1.5	15	kΩ
Voltage Feedback Ratio	Itage Feedback Ratio $(I_{C} = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz})$		0.1	8.0	X 10-4
mall-Signal Current Gain $(I_C = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz})$		h _{fe}	60	500	-
Output Admittance $(I_{C} = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz})$		h _{oe}	1.0	100	μMhos
SWITCHING CHARACTERISTICS					
Delay Time (V _{CC} = -30 Vdc, V _{EB} = -		t _d	-	15	00
Rise Time			-	20	ns
Storage Time	$(V_{CC} = -30 \text{ Vdc}, I_C = -150 \text{ mAdc},$	ts	-	225	ns
Fall Time	$I_{B1} = I_{B2} = -15 \text{ mAdc}$	t.		20	113

Fall Time t_f Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

 $I_{B1} = I_{B2} = -15 \text{ mAdc}$

3. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%.

SWITCHING TIME EQUIVALENT TEST CIRCUIT

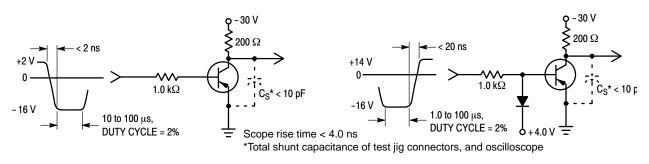


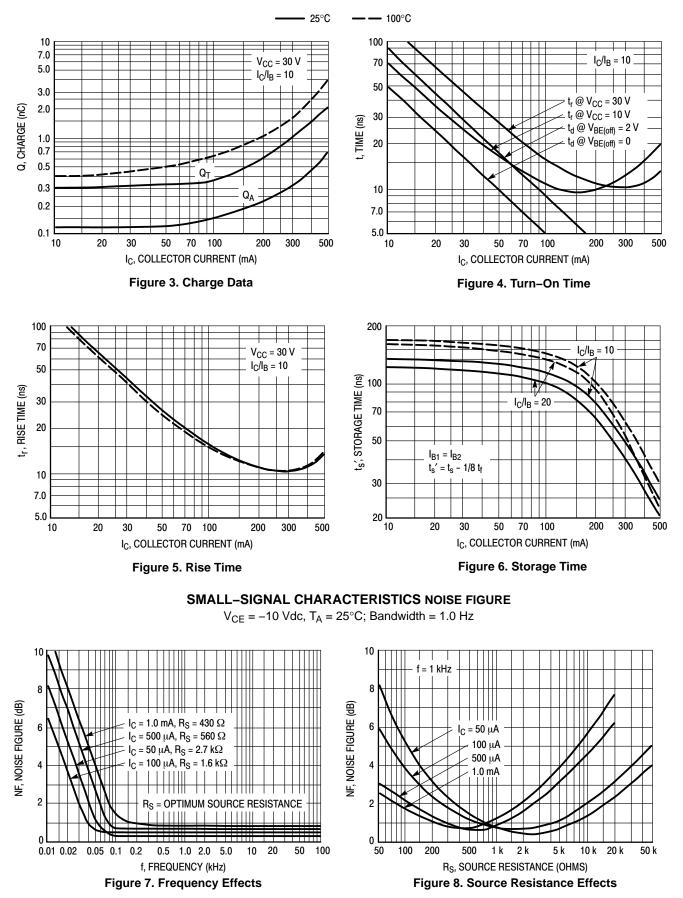
Figure 1. Turn-On Time

Figure 2. Turn-Off Time

_

30

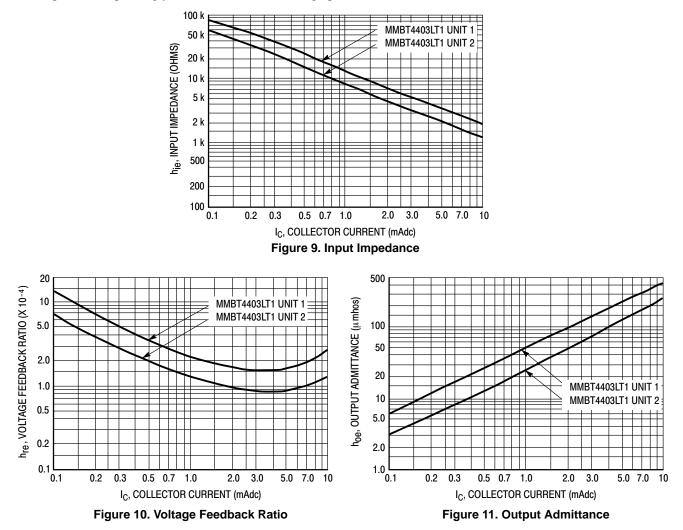
TRANSIENT CHARACTERISTICS



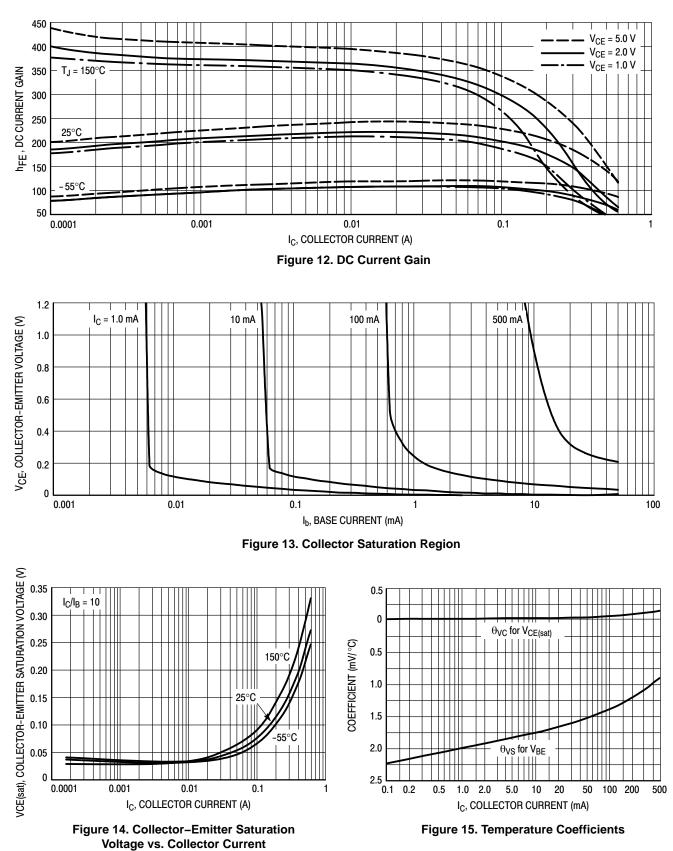
h PARAMETERS

V_{CE} = 10 Vdc, f = 1.0 kHz, T_A = 25°C

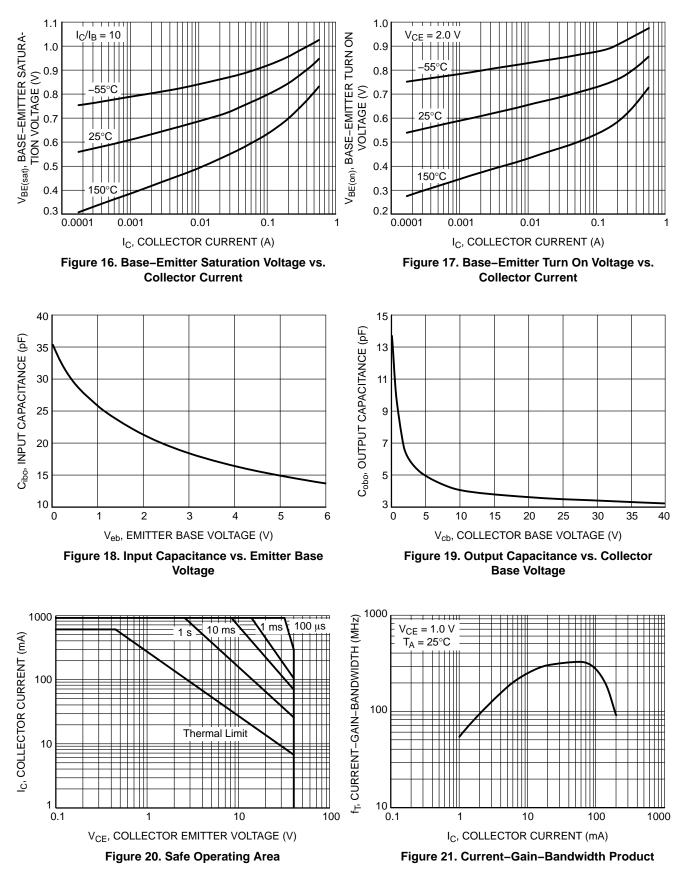
This group of graphs illustrates the relationship between h_{fe} and other "h" parameters for this series of transistors. To obtain these curves, a high–gain and a low–gain unit were selected from the MMBT4403LT1 lines, and the same units were used to develop the correspondingly numbered curves on each graph.



STATIC CHARACTERISTICS



STATIC CHARACTERISTICS



MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

D

3

TOP VIEW

SIDE VIEW

Нe

DETAIL A

-3X b

onsemi



SCALE 4:1

A _ ' A1SOT-23 (TO-236) CASE 318 ISSUE AT

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-L1

DETAIL A

END VIEW

DATE 01 MAR 2023

NDTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIM	IETERS			INCHES	
DIM	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
с	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
Η _E	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10*	0*		10*



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code

= Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

onsemi

SOT-23 (TO-236) CASE 318 ISSUE AT

DATE 01 MAR 2023

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE		
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE	2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE	3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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